SEMITOP®4

3-phase bridge rectifier + brake chopper + 3-phase bridge inverter

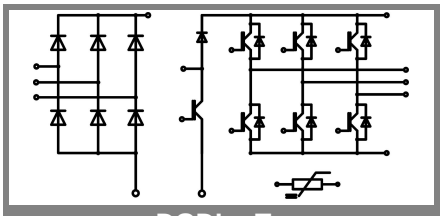
SK 50 DGDL 12T4 T

Target Data

Features

- One screw mounting module
- Fully compatible with SEMITOP®1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench4 IGBT technology
- CAL4 technology free-wheeling diode
- Integrated NTC temperature sensor

1) $V_{CE,sat}$, V_F = chip level value



DGDL - T

Absolute Maximum Ratings		Ts = 25 °C, unless otherwise specified	
Symbol	**Conditions**	**Values**	**Units**
IGBT - Inverter.For IGBT chopper maximum ratings, please refer to SK35DGDL12T4T			
V_{CES}		1200	V
I_C	T_s = 25 (70) °C	75 (60)	A
I_{CRM}	I_{CRM}= 3 x I_{Cnom}, t_p = 1 ms	150	A
V_{GES}		± 20	V
T_j		-40 ... +175	°C
Diode - Inverter,Chopper			
I_F	T_s = 25 (70) °C	60 (45)	A
I_{FRM}	I_{FRM} = 2xI_{Fnom}, t_p = 1 ms	150	A
T_j		-40 ... +150	°C
Rectifier			
V_{RRM}		1600	V
I_F	T_s = 70 °C	61	A
I_{FSM} / I_{TSM}	t_p = 10 ms , sin 180 ° ,T_j = 25 °C	700	A
I^2t	t_p = 10 ms , sin 180 ° ,T_j = 25 °C	2400	A²s
T_j		-40 ... +175	°C
T_{sol}	Terminals, 10 s	260	°C
T_{stg}		-40 ... +125	°C
V_{isol}	AC, 1 min. / 1 s	2500 / 3000	V

Characteristics		Ts = 25 °C, unless otherwise specified			
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
IGBT - Inverter. For IGBT chopper electrical characteristics, please refer to SK35DGDL12T4T					
V_{CEsat}	I_C = 50 A, T_j = 25 (150) °C		1,85 (2,2)	2,05 (2,45)	V
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 1,7 mA	5	5,8	6,5	V
$V_{CE(TO)}$	T_j = 25 °C (150) °C		1,1 (1)	1,3 (1,2)	V
r_T	T_j = 25 °C (150) °C		15 (24)		mΩ
C_{ies}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		2,77		nF
C_{oes}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		0,2		nF
C_{res}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		0,16		nF
$R_{th(j-s)}$	per IGBT		0,65		K/W
$t_{d(on)}$	under following conditions		63		ns
t_r	V_{CC} = 600 V, V_{GE} = ± 15 V		65		ns
$t_{d(off)}$	I_C = 50 A, T_j = 150 °C		521		ns
t_f	R_{Gon} = R_{Goff} = 32 Ω		80		ns
E_{on}	inductive load		8,3		mJ
E_{off}			5		mJ
Diode - Inverter,Chopper					
V_F = V_{EC}	I_F = 50 A, T_j = 25(150) °C		2,22 (2,18)	2,54 (2,5)	V
$V_{(TO)}$	T_j = 25 °C (150) °C		1,3 (0,9)	1,5 (1,1)	V
r_T	T_j = 25 °C (150) °C		18,4 (25,6)	20,8 (28)	mΩ
$R_{th(j-s)}$	per diode		0,97		K/W
I_{RRM}	under following conditions		30		A
Q_{rr}	I_F = 50 A, V_R = 300 V		7,2		µC
E_{rr}	V_{GE} = 0 V, T_j = 150 °C		2,15		mJ
	$di_{F/dt}$ = 920 A/µs				
Diode - Rectifier					
V_F	I_F = 50 A, T_j = 25(150) °C		1,1		V
$V_{(TO)}$	T_j = 150 °C		0,8		V
r_T	T_j = 150 °C		6		mΩ
$R_{th(j-s)}$	per diode		0,9		K/W
Temperatur sensor					
R_{ts}	5 %, T_r = 25 (100) °C		5000(493)		Ω
Mechanical data					
w			60		g
M_s	Mounting torque		3,5		Nm

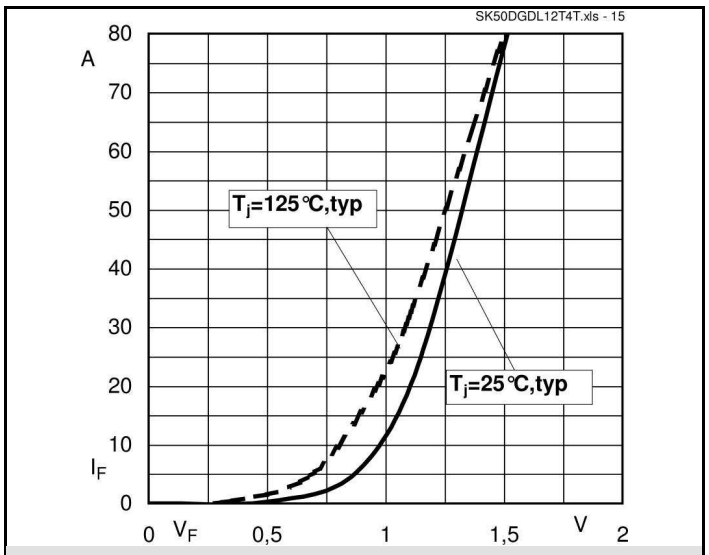


Fig.15 Input bridge Diode forward characteristic

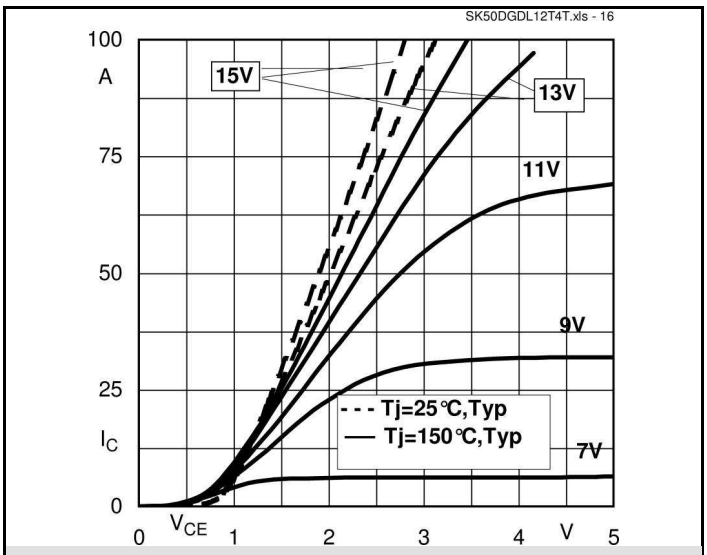


fig.16 Typical Output characteristic

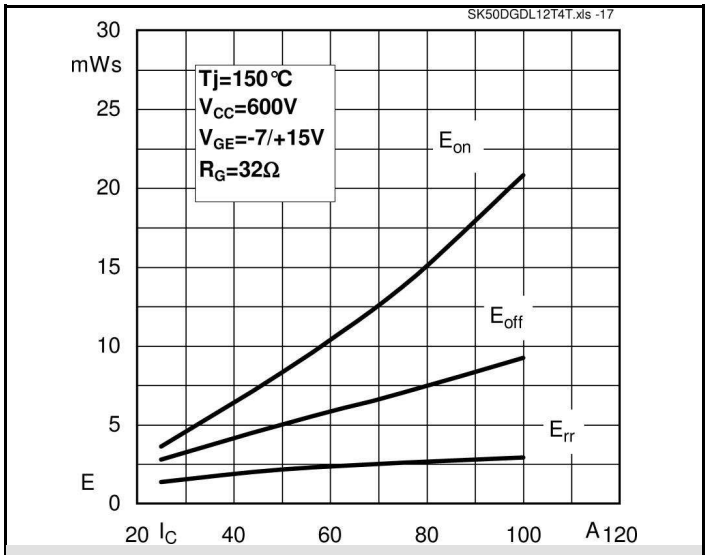


Fig.17 Turn-on/-off energy=f(Ic)

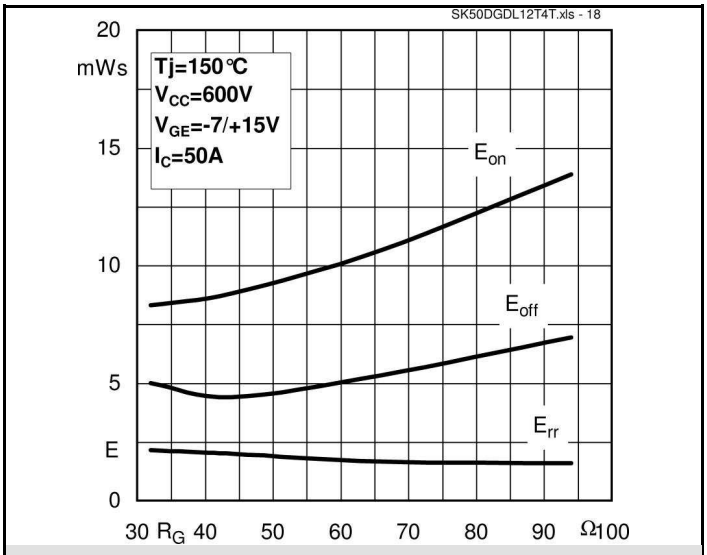


Fig.18 Turn-on/-off energy=f(Rg)

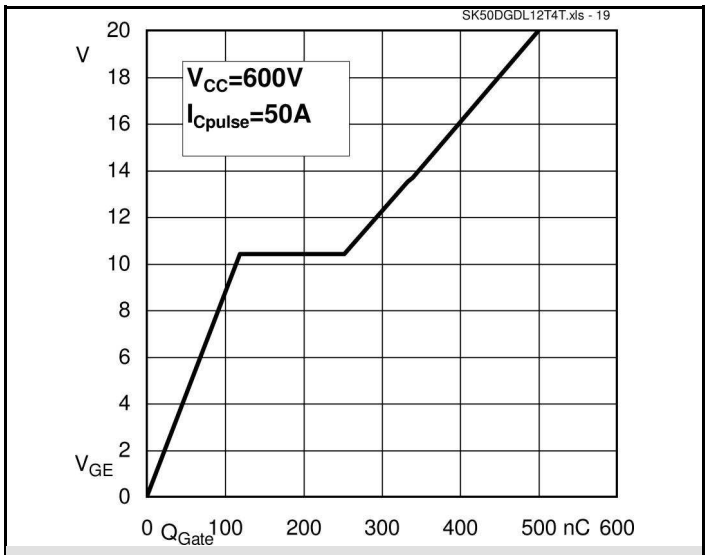


Fig.19 Typical gate charge characteristic

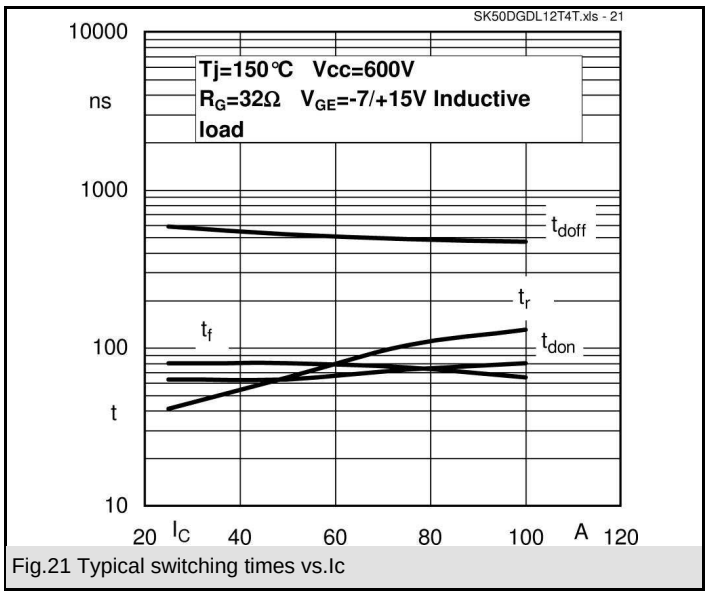


Fig.21 Typical switching times vs.Ic

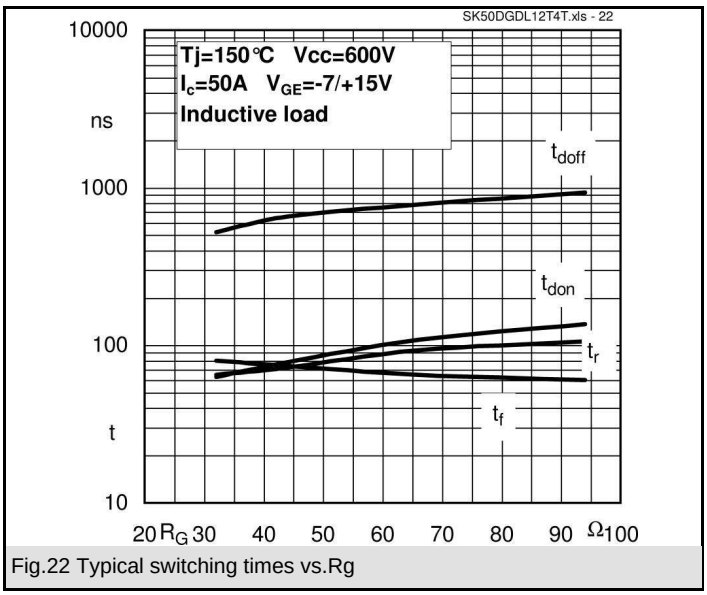


Fig.22 Typical switching times vs.Rg

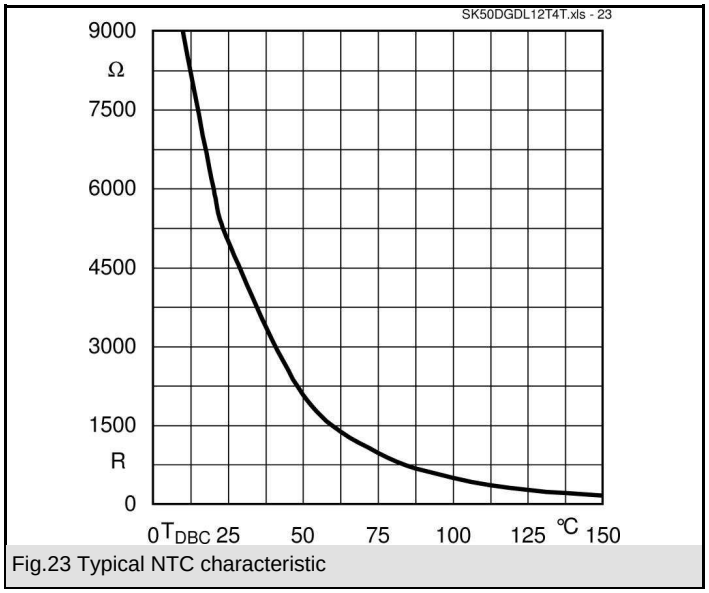
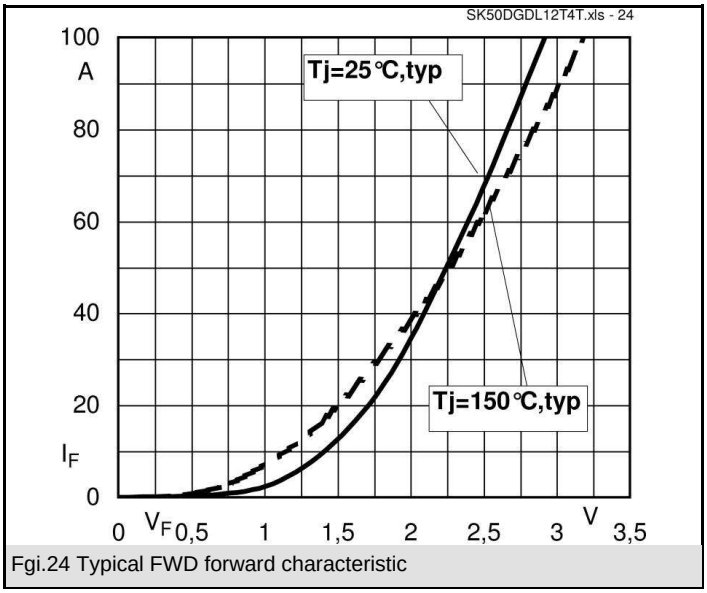
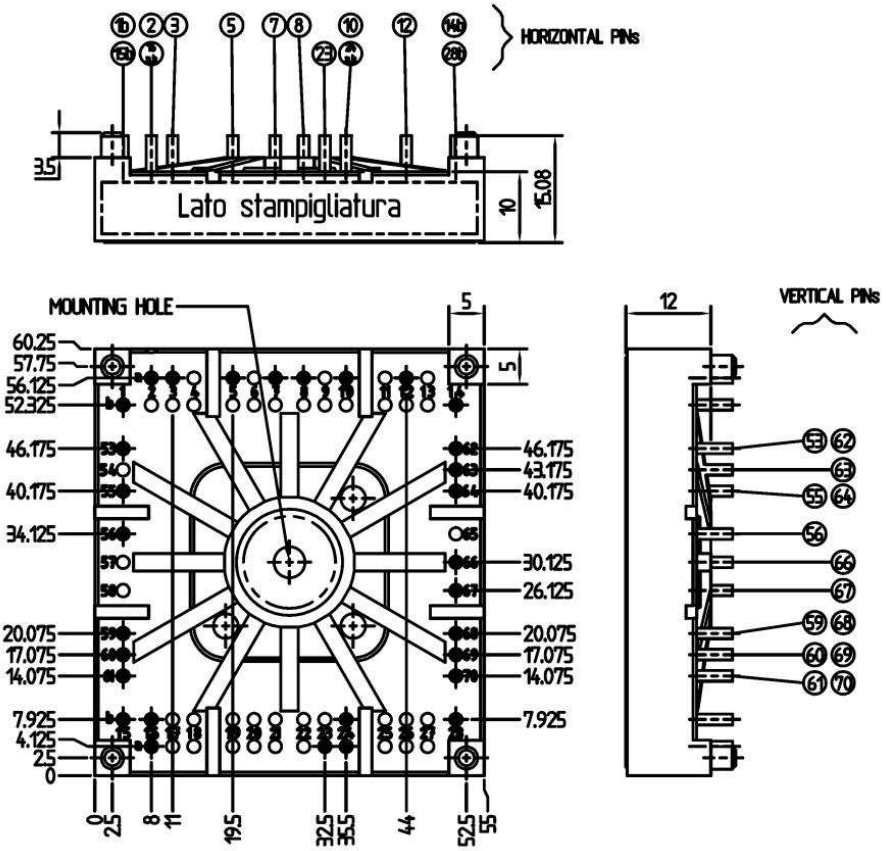


Fig.23 Typical NTC characteristic

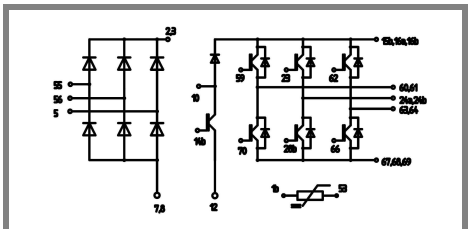


Fgi.24 Typical FWD forward characteristic

Dimensions in mm



Case T 75 (Suggested hole diameter for the solder pins in the circuit board: 2mm. Suggested hole diameter for the mounting pins in the circuit board: 3,6mm)



Case T 75 (pin without letter refers to row "a", unless otherwise specified)

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

